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- said sled members in a dynamically balanced relationship;
- abrasive feed means connected to said source of electrical power to continuously apply a stream of liquid abrasive to said blades; and
- a disabling circuit coupled to said motor and abrasive feed means and coacting with each of said bodies to deactivate said motor and abrasive feed means when the last of said bodies has been sliced.
12. A device for simultaneously cutting into slices a plurality of semiconductor crystal bodies comprising:
- a frame member;
 - a plurality of sled members each positioned in said frame member for independent reciprocation thereon;
 - a carrier member retained in each of said sled members for movement therewith;
 - a blade assembly having at least two relatively thin metal ribbon blades adapted to provide a pair of parallel cutting edges spaced by a distance proportional to the thickness of the slice to be cut from one of said bodies, said blades being mounted in said carrier member;
 - a plurality of supporting means each adapted to support one of said crystal bodies, said supporting means being arranged relative to said sled members for edgewise engagement of said blades with said bodies under resilient pressure;
 - a retracting means coupled to each of said supporting means to separate said blades and bodies when said bodies have been sliced;
 - a source of electrical power;
 - an electric motor electrically coupled to said source of electrical power and mechanically coupled to said sled members to simultaneously reciprocate each of said sled members in a dynamically balanced relationship;
 - abrasive feed means connected to said source of electrical power including a pump and reservoir to continuously apply a liquid abrasive to said blades; and
 - a disabling circuit including a plurality of normally closed electrical switches connected in parallel to said motor and abrasive feed means and to said source of electrical power each being located in juxtaposition to one of said retracting means for actuation thereby to disable said motor and abrasive feed means when the last of said bodies has been sliced.
13. A device for simultaneously cutting into slices a plurality of semiconductor crystal bodies comprising:
- a frame member;
 - a plurality of sled members each positioned on said frame member for independent reciprocation thereon;
 - a carrier member retained in each of said sled members for movement therewith;
 - a blade assembly having at least two relatively thin metal ribbon blades adapted to provide a pair of parallel cutting edges spaced by a distance proportional to the thickness of the slice to be cut from one of said bodies, said blades being mounted in said carrier member;
 - a plurality of supporting platforms each adapted to be pivoted about a first end and having a body mounted to a second end and a changeable weight means coupled to said platform at said first end for positioning said body relative to said sled members for edgewise engagement of said blades therewith under resilient pressure;
 - a retracting means included in said changeable weight means for separating said blades and bodies when each of said bodies has been sliced;
 - a source of electrical power;
 - an electric motor electrically coupled to said source of electrical power and mechanically coupled to said

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- sled members to simultaneously reciprocate each of said sled members in a dynamically balanced relationship;
- abrasive feed means connected to said source of electrical power including a pump and reservoir to continuously apply a liquid abrasive to said blades; and
- a disabling circuit coupled to said motor and said abrasive feed means and to said source of electrical power, said circuit including a plurality of normally closed electrical switches each of which is located in juxtaposition to one of said retracting means for actuation thereby, said switches being electrically connected in parallel between said source of electrical power and said motor and abrasive feed means whereby when the last of said switches is actuated the electrical path between said source of power and said motor and abrasive feed means will be interrupted.
14. A device for simultaneously cutting into slices a plurality of semiconductor crystal bodies comprising:
- a frame member;
 - a plurality of sled members each positioned on said frame member for independent reciprocation thereon;
 - a carrier member retained in each of said sled members for movement therewith;
 - a blade assembly having at least two relatively thin metal ribbon blades adapted to provide a pair of parallel cutting edges spaced by a distance equal to the thickness of the slice to be cut from one of said bodies, said blades being mounted in said carrier member;
 - a plurality of supporting platforms each adapted to be pivoted about a first end and having a body mounted to a second end and a changeable weight means to said platform at said first end for positioning said body relative to said sled members for edgewise engagement of said blades therewith under resilient pressure;
 - a retracting means included in said changeable weight means for separating said blades and bodies when each of said bodies has been sliced;
 - a source of electrical power;
 - an electrical motor electrically coupled to said source of electrical power and mechanically coupled to said sled members to simultaneously reciprocate each of said sled members in a dynamically balanced relationship;
 - abrasive feed means having connected to said source of electrical power including a pump and reservoir to continuously apply a liquid abrasive to said blades; and
 - a disabling circuit coupled to said motor and abrasive feed means, said circuit including a plurality of parallel connected insulation covered electrical conductors each of which is coupled to said source of electrical power and to said motor and abrasive feed means and includes a portion mounted adjacent to one of said bodies whereby the blades slicing through said bodies will sever the insulation of said conductors and will disable said motor and abrasive feed means when the last of said conductor portions is severed.

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